

AMENDMENTS TO THE CLAIMS

Claims 1-25 Cancelled without prejudice or disclaimer.

26. Cancelled without prejudice or disclaimer.

27. Cancelled without prejudice or disclaimer.

28. Cancelled without prejudice or disclaimer.

29. Cancelled without prejudice or disclaimer.

Claims 30-37 Cancelled without prejudice or disclaimer.

Claims 38-44 Cancelled without prejudice or disclaimer.

Claims 45-58 Cancelled without prejudice or disclaimer.

59. (Previously Presented) An imaging device comprising:
an image sensor subassembly including an image sensor mounted on a
printed circuit board;

a substantially rigid optical subassembly, said optical subassembly including
an optical element disposed on a substantially rigid member;

at least one solderable surface formed on either of said printed circuit board
or said optical subassembly defining at least one solder receiving interface between
said printed circuit board and said optical subassembly; and

solder material for bonding said subassemblies disposed at said at least one
solder-receiving interface.

60. (Previously Presented) The device of claim 59, further including a
housing encapsulating said device, said device partially defining a feed path.

61. (Previously Presented) The device of claim 59, further including a
housing encapsulating said device, said housing including a handle.

62. (Previously Presented) The device of claim 59, wherein said at least one solderable surface is made in an irregular configuration having an increased surface area per unit three dimensional space relative to that of a smooth surface.

63. (Previously Presented) The device of claim 59, wherein said at least one solderable surface is made in the configuration of a hole.

64. (Previously Presented) The device of claim 59, wherein said at least one solderable surface is in the configuration of a pin.

65. (Previously Presented) The device of claim 59, wherein said at least one solderable surface is provided by a threaded screw.

66. (Previously Presented) An imaging device comprising:
an image sensor subassembly including an image sensor mounted on a printed circuit board;
a substantially rigid optical subassembly, said optical subassembly having a single receive optical axis and including an optical element disposed on a substantially rigid member;
at least one solderable surface formed on either of said image sensor subassembly or optical subassembly defining at least one solder receiving interface between said image sensor subassembly and said optical subassembly; and
solder material for bonding said subassemblies disposed at said at least one solder-receiving interface.

67. (Previously Presented) The device of claim 66, further comprises a housing encapsulating said device said housing partially defining a feed path for receiving documents.

68. (Previously Presented) The device of claim 66, further comprising a housing encapsulating said device said housing including a handle.

69. (Previously Presented) The device of claim 66, wherein said at least one solderable surface is made in an irregular configuration having an increased surface area per unit three dimensional space relative to that of a smooth surface.

70. (Previously Presented) The device of claim 66, wherein said at least one solderable surface is made in the configuration of a hole.

71. (Previously Presented) The device of claim 66, wherein said at least one solderable surface is in the configuration of a pin.

Claim 72 Cancelled without prejudice or disclaimer.

73. (Previously Presented) An optical reading device comprising:
an optical and image sensor assembly including
an image sensor subassembly including an image sensor mounted on a substantially rigid planar member,
an optical subassembly, said optical subassembly including an optical element disposed on a substantially rigid member,
at least one solderable surface formed on either of said optical subassembly or said substantially rigid planar member defining at least one solder receiving interface between said substantially rigid planar member and said optical subassembly,
solder material for bonding said subassemblies disposed at said at least one solder-receiving interface,
a housing, said optical and image sensor assembly being disposed in said housing.

74. (Previously Presented) The device of claim 73, wherein said housing partially defines a feed path and wherein said device is a document reading device, for reading indicia from documents transported along said feed path.

75. (Previously Presented) The device of claim 73, wherein said housing includes a handle, and wherein said device is a hand held optical reader.

76. (Previously Presented) The device of claim 73, wherein said at least one solderable surface is made in an irregular configuration having an increased surface area per unit three dimensional space relative to that of a smooth surface.

77. (Previously Presented) The device of claim 73, wherein said at least one solderable surface is made in the configuration of a hole.

78. (Previously Presented) The device of claim 73, wherein said at least one solderable surface is in the configuration of a pin.

79. (Previously Presented) The device of claim 73, wherein said at least one solderable surface is provided by a threaded screw.

Claims 80-108 Cancelled without prejudice or disclaimer.